AUTOMOTIVE GRADE



AUIRF4905

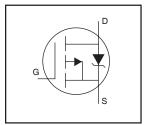
HEXFET® Power MOSFET

Features

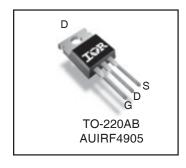
- Advanced Planar Technology
- Low On-Resistance
- Dynamic dV/dT Rating
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- · Repetitive Avalanche Allowed up to Timax
- Lead-Free, RoHS Compliant
- Automotive Qualified *

Description

Specifically designed for Automotive applications, this cellular design of HEXFET® Power MOSFETs utilizes the latest processing techniques to achieve low on-resistance per silicon area. This benefit combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in Automotive and a wide variety of other applications.



V _{(BR)DSS}	- 55V
R _{DS(on)} max.	0.02 Ω
I _D	-74A



G	D	S
Gate	Drain	Source

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T_A) is $25^{\circ}C$, unless otherwise specified.

	Parameter	Max.	Units
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ -10V	-74	
I _D @ T _C = 100°C	Continuous Drain Current, V _{GS} @ -10V	-52	А
I _{DM}	Pulsed Drain Current ①	-260	
P _D @T _C = 25°C	Power Dissipation	200	W
	Linear Derating Factor	1.3	W/°C
V _{GS}	Gate-to-Source Voltage	± 20	V
E _{AS}	Single Pulse Avalanche Energy(Thermally limited) ②	930	mJ
AR Avalanche Current ①		-38	Α
Repetitive Avalanche Energy ①		20	mJ
dv/dt	Peak Diode Recovery dv/dt ③	-5.0	V/ns
TJ	Operating Junction and	-55 to + 175	
T _{STG}	Storage Temperature Range		°C
	Soldering Temperature, for 10 seconds(1.6mm from case)	300	
	Mounting Torque, 6-32 or M3 screw	10 lbf•in (1.1N•m)	

Thermal Resistance

	Parameter	Тур.	Max.	Units
R _{eJC}	Junction-to-Case ⑦		0.75	
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	0.50	_	°C/W
$R_{\theta,JA}$	Junction-to-Ambient		62	

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^{*}Qualification standards can be found at http://www.irf.com/

Static Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	-55			V	$V_{GS} = 0V, I_{D} = -250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient		-0.05		V/°C	Reference to 25°C, I _D = -1mA
R _{DS(on)}	Static Drain-to-Source On-Resistance			0.02	Ω	V _{GS} = -10V, I _D = -38A ④
V _{GS(th)}	Gate Threshold Voltage	-2.0		-4.0	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$
gfs	Forward Transconductance	21			S	$V_{DS} = -25V, I_{D} = -38A$
I _{DSS}	Drain-to-Source Leakage Current			-25	μΑ	$V_{DS} = -55V, V_{GS} = 0V$
				-250		$V_{DS} = -44V, V_{GS} = 0V, T_{J} = 150^{\circ}C$
I _{GSS}	Gate-to-Source Forward Leakage			100	nA	V _{GS} = 20V
	Gate-to-Source Reverse Leakage			-100		$V_{GS} = -20V$
	•	•				145 201
-	ectrical Characteristics @ T _J = 25°C (unless o	otherwi		cified)	I _D = -38A
Qg		unless o	otherwi	se spec		
Q _g Q _{gs}	Total Gate Charge	unless o	otherwi	se spec		I _D = -38A
Q _g Q _{gs} Q _{gd}	Total Gate Charge Gate-to-Source Charge	unless (otherwis	180 32		$I_D = -38A$ $V_{DS} = -44V$
$\begin{array}{c} \textbf{Dynamic} \textbf{Ele} \\ \textbf{Q}_g \\ \textbf{Q}_{gs} \\ \textbf{Q}_{gd} \\ \textbf{t}_{d(on)} \\ \textbf{t}_r \end{array}$	Total Gate Charge Gate-to-Source Charge Gate-to-Drain ("Miller") Charge	— — —		180 32 86		I_D = -38A V_{DS} = -44V V_{GS} = -10V , See Fig.6 and 13 $^{\textcircled{4}}$

96

4.5

7.5

3400

1400

640

 $R_D = 0.72 \Omega$ See Fig. 10 \oplus

and center of die contact

f = 1.0MHz, See Fig.5

Between lead,

6mm (0.25in.)

from package

 $V_{GS} = 0V$

 $V_{DS} = -25V$

Diode Characteristics

Fall Time

Internal Drain Inductance

Internal Source Inductance

Reverse Transfer Capacitance

Input Capacitance

Output Capacitance

	Parameter	Min.	Тур.	Max.	Units	Conditions
I _S	Continuous Source Current			-74		MOSFET symbol
	(Body Diode)			-74	Α	showing the
I _{SM}	Pulsed Source Current			-260		integral reverse
	(Body Diode) ①			-200		p-n junction diode.
V _{SD}	Diode Forward Voltage			-1.6	V	T _J = 25°C, I _S =-38A , V _{GS} = 0V ④
t _{rr}	Reverse Recovery Time		89	130	ns	$T_J = 25$ °C, $I_F = -38A$
Q _{rr}	Reverse Recovery Charge		230	350	nC	di/dt = -100A/µs ⊕
t _{on}	Forward Turn-On Time	Intrinsic	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)			

Notes:

 L_D

Ls

 C_{iss}

Coss

 C_{rss}

- $\ensuremath{\mathbb{O}}$ Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- ② Starting T_J = 25°C, L = 1.3mH R_G = 25 Ω , I_{AS} = -38A. (See Figure 12)
- $\begin{tabular}{l} \begin{tabular}{l} \begin{tab$
- 4 Pulse width \leq 300 μ s; duty cycle \leq 2%.

Qualification Information[†]

		Automotive			
		(per AEC-Q101) ^{††}			
		Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.			
Moisture Sensi	Moisture Sensitivity Level 3L-TO-220 N/A				
	Machine Madel	Class M4 (425V)			
	Machine Model	(per AEC-Q101-002)			
FOD	Llamana Dada Madal	Class H2 (4000V)			
ESD	Human Body Model	(per AEC-Q101-001)			
		Class C5 (1125V)			
	Charged Device Model		(per AEC-Q101-005)		
RoHS Complia	nt	Yes			

[†] Qualification standards can be found at International Rectifier's web site: http://www.irf.com/

^{††} Exceptions to AEC-Q101 requirements are noted in the qualification report.

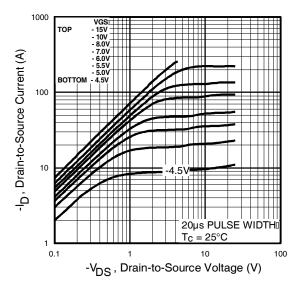


Fig 1. Typical Output Characteristics

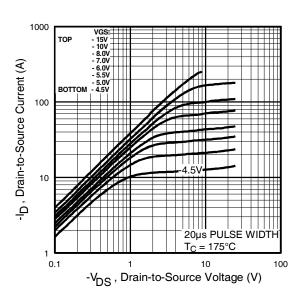


Fig 2. Typical Output Characteristics

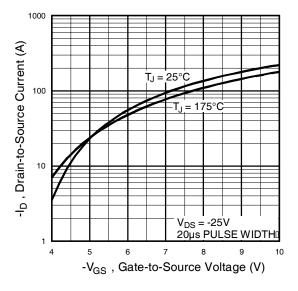


Fig 3. Typical Transfer Characteristics

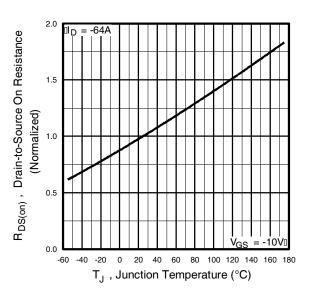


Fig 4. Normalized On-Resistance Vs. Temperature

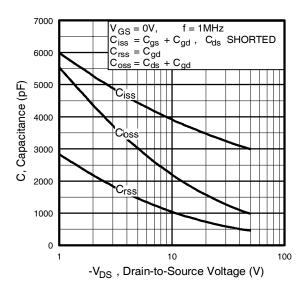


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

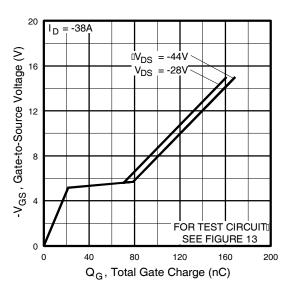


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

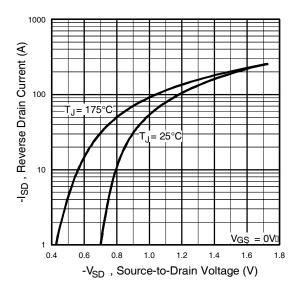


Fig 7. Typical Source-Drain Diode Forward Voltage

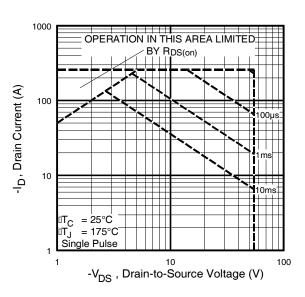


Fig 8. Maximum Safe Operating Area

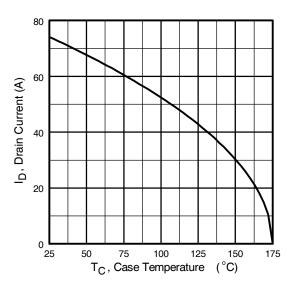


Fig 9. Maximum Drain Current Vs. Case Temperature

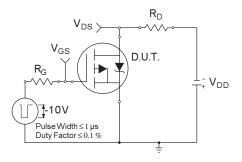


Fig 10a. Switching Time Test Circuit

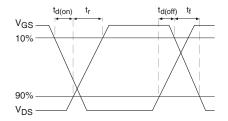


Fig 10b. Switching Time Waveforms

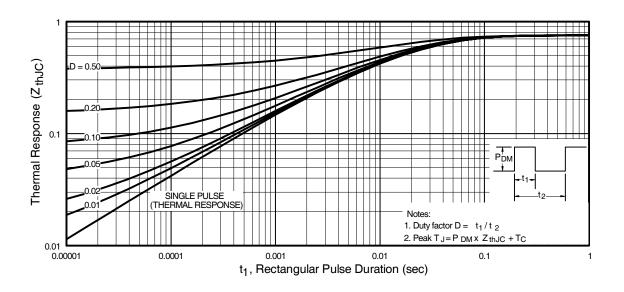


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

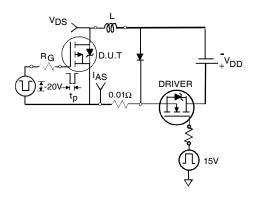
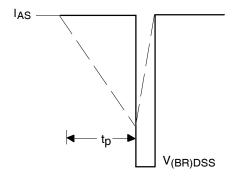


Fig 12a. Unclamped Inductive Test Circuit



 $\textbf{Fig 12b.} \ \ \textbf{Unclamped Inductive Waveforms}$

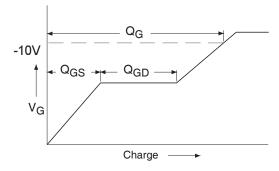


Fig 13a. Basic Gate Charge Waveform

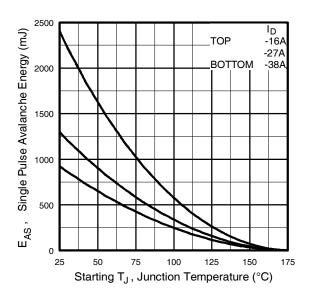


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

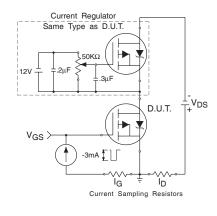
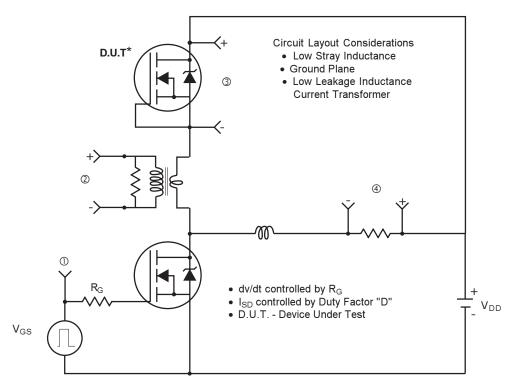
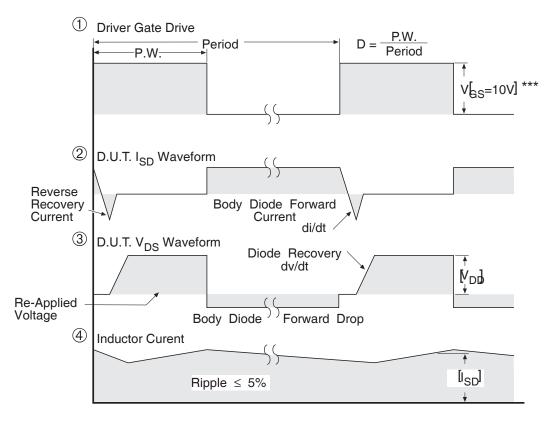


Fig 13b. Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit



^{*} Reverse Polarity of D.U.T for P-Channel

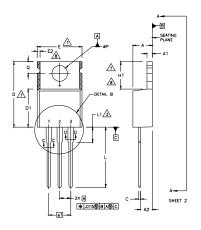


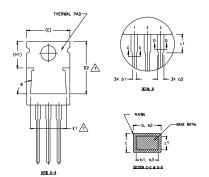
*** V_{GS} = 5.0V for Logic Level and 3V Drive Devices

Fig 14. For P-Channel HEXFETS

TO-220AB Package Outline

Dimensions are shown in millimeters (inches)





NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
- DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS].
- LEAD DIMENSION AND FINISH UNCONTROLLED IN L1.
- DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- - DIMENSION b1 & c1 APPLY TO BASE METAL ONLY.
 - CONTROLLING DIMENSION : INCHES.
- THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS E,H1,D2 & E1
- DIMENSION E2 X H1 DEFINE A ZONE WHERE STAMPING AND SINGULATION IRREGULARITIES ARE ALLOWED.

	DIMENSIONS					
SYMBOL	MILLIMETERS		INC			
	MIN.	MAX.	MIN.	MAX.	NOTES	
Α	3.56	4.82	,140	.190		
A1	0.51	1,40	.020	.055		
A2	2.04	2.92	.080	.115		
b	0.38	1.01	.015	.040		
b1	0.38	0,96	.015	.038	5	
b2	1,15	1.77	.045	.070		
b3	1.15	1,73	.045	.068		
С	0.36	0.61	.014	.024		
c1	0.36	0.56	.014	.022	5	
D	14.22	16,51	.560	.650	4	
D1	8.38	9.02	.330	.355		
D2	12.19	12.88	.480	.507	7	
E	9.66	10.66	.380	.420	4,7	
E1	8.38	8.89	.330	.350	7	
e	2.54		.100	BSC		
e1	5,	08	.200	BSC		
H1	5.85	6.55	.230	.270	7,8	
L	12.70	14.73	.500	.580		
L1	-	6.35	-	.250	3	
øΡ	3.54	4.08	.139	.161		
Q	2.54	3,42	,100	.135		
ø	90*-	-93 °	90*	-93°	1	

LEAD ASSIGNMENTS

HEXFET

1,- GATE 2.- DRAIN 3.- SOURCE

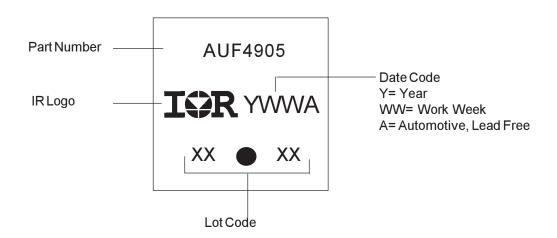
IGBTs, CoPACK

1.- GATE 2.- COLLECTOR 3.- EMITTER

DIODES

1.- ANODE/OPEN 2.- CATHODE 3.- ANODE

TO-220AB Part Marking Information



Ordering Information

Base part	Package Type	Standard Pack		Complete Part Number
		Form	Quantity	
AUIRF4905	TO-220	Tube	50	AUIRF4905

AUIRF4905



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